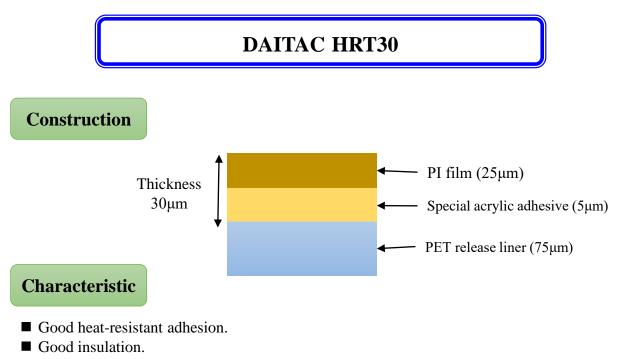
## **TECHNICAL INFORMATION**



## Heat resistance PI carrier adhesive tape



## Application

- For heat resistance.
- For insulation around substrate.

## Property

		HRT30
Tape thickness	μm	30
Adhesion (SUS) [N/25mm]	23°C50%RH	3.0
Holding power 500g weight	150°C×24h	No falling



- 980mm in max width / 50m in length
- DIC Corporation Composite Material Product div.

http://www.dic-global.com/en/

Items mentioned in this information are for customers ' reference and limited to certain examples although they are based on the most reliable data obtained by our company. It is hoped that customers make the best use of these products after careful examination. Concerning to use and processing the products on this documents, it is not guaranteed a industrial ownerships of a third party. All recipes and processes should be modified, if necessary to conform with particular application.